

### Product Summary

- $V_{DS}$  60 V
- $I_{DS}$  80A
- $R_{DS(ON)}$  (at  $V_{GS}=10$ )  $\leq 5.8m\Omega$  (Typ)
- Low Gate Charge Minimize Switching Loss

### Application

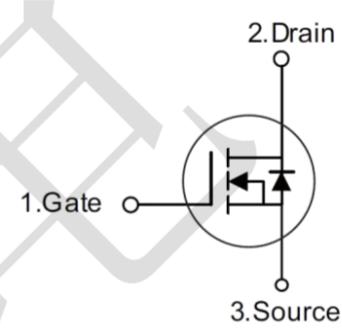
- Adaptor
- Charger
- Power management
- SMPS Standby Power

### Package and Pin Configuration



T0-252

### Circuit diagram



### Absolute Maximum Ratings

( $T_A=25^\circ\text{C}$  unless otherwise noted)

PARAMETER	SYMBOL	Value	UNIT
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	80	A
Continuous Drain Current ( $T_C=100^\circ\text{C}$ )	$I_D$	42	A
Pulsed Drain Current (Note 1)	$I_{DM}$	270	A
Maximum Power Dissipation @ $T_A=25^\circ\text{C}$	$P_D$	100	W
Operating Junction Temperature Range	$T_J$	+150	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-55 to +150	$^\circ\text{C}$
Thermal Resistance, Junction to Case	$R_{\theta JC}$	2.1	$^\circ\text{C}/\text{W}$

Note : When mounted on 1" square PCB (FR4 material).

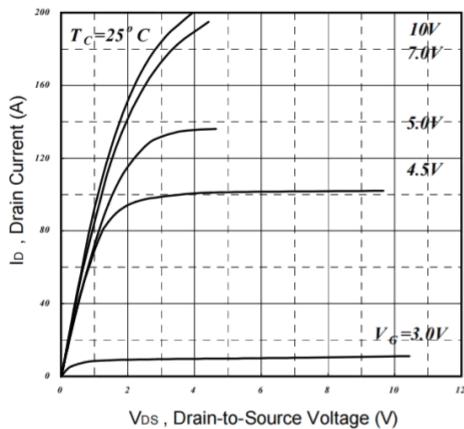
**Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	BV <sub>DSS</sub>	60	--	--	V
Gate-Source Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	V <sub>GS(th)</sub>	1.5	3.0	4.5	V
Gate-Source Leakage	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V	I <sub>GSS</sub>	--	--	±100	nA
Zero Gate Voltage Drain Current	V <sub>DS</sub> = 60V, V <sub>GS</sub> =0V	I <sub>DSS</sub>	--	--	10	μA
Drain-Source On-State Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 40A	R <sub>Ds(on)</sub>	--	5.8	6.8	mΩ
	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 20A		--	7.5	9.6	mΩ
Forward Trans conductance	V <sub>DS</sub> =10V,I <sub>D</sub> =30A	g <sub>FS</sub>	--	70	--	S
<b>Dynamic</b> (Note 2)						
Total Gate Charge (Note 3)	V <sub>DS</sub> = 48V, I <sub>D</sub> =30A, V <sub>GS</sub> = 4.5V	Q <sub>g</sub>	--	33	--	nC
Gate-Source Charge (Note 3)		Q <sub>gs</sub>	--	5.0	--	
Gate-Drain Charge (Note 3)		Q <sub>gd</sub>	--	21	--	
Input Capacitance	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, F= 1.0MHz	C <sub>iss</sub>	--	2660	--	pF
Output Capacitance		C <sub>oss</sub>	--	280	--	
Reverse Transfer Capacitance		C <sub>rss</sub>	--	200	--	
<b>Switching</b>						
Turn-On Delay Time (Note 3)	V <sub>DD</sub> = 30V, I <sub>D</sub> = 30A, V <sub>GS</sub> = 10V, R <sub>G</sub> = 3.3Ω	t <sub>d(on)</sub>	--	10	--	nS
Rise Time (Note 3)		t <sub>r</sub>	--	42	--	
Turn-Off Delay Time (Note 3)		t <sub>d(off)</sub>	--	46	--	
Fall Time (Note 3)		t <sub>f</sub>	--	80	--	
<b>Source-Drain Diode Ratings and Characteristics</b> (Note 2)						
Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 10A	V <sub>SD</sub>	--	0.8	1.2	V
Continuous Source Current	Integral reverse diode in the MOSFET	I <sub>S</sub>	--	--	80	A
Pulsed Current (Note 1)		I <sub>SM</sub>	--	--	270	A
Reverse recovery time	V <sub>GS</sub> =0V ,I <sub>F</sub> =20A, diF/dt=-100A/μs	t <sub>rr</sub>	--	25	--	nS
Reverse recovery charge		Q <sub>rr</sub>	--	24	--	nC

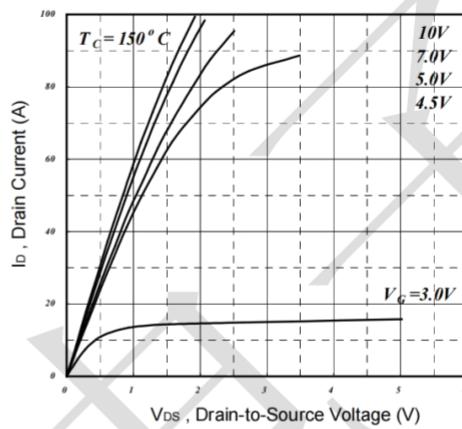
Notes:

1. Pulse test; pulse width ≤ 300 μS, duty cycle ≤ 1%.
2. Guaranteed by design, not subject to production testing.
3. Independent of operating temperature

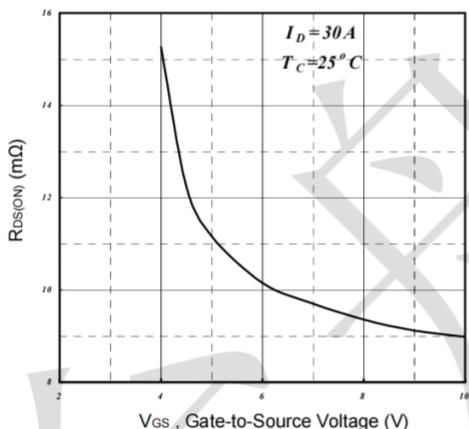
### TYPICAL CHARACTERISTICS ( $T_A=25^\circ\text{C}$ unless otherwise noted)



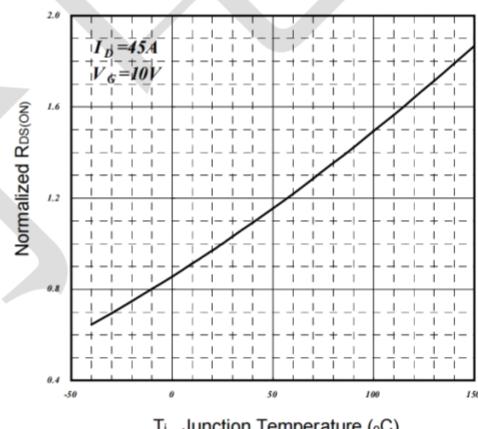
Typical Output Characteristics



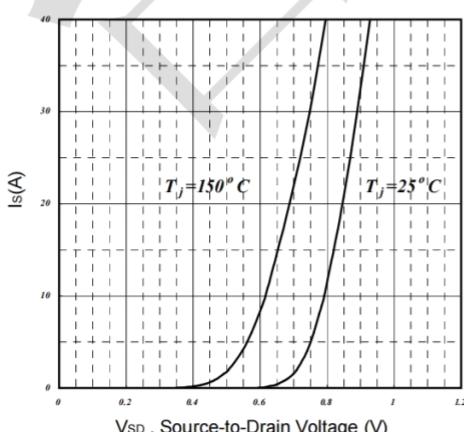
Typical Output Characteristics



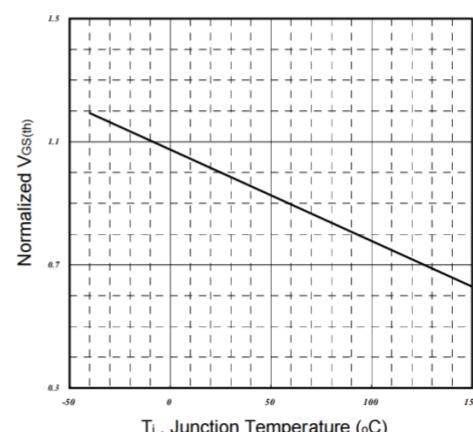
On-Resistance v.s. Gate Voltage



Normalized On-Resistance  
v.s. Junction Temperature



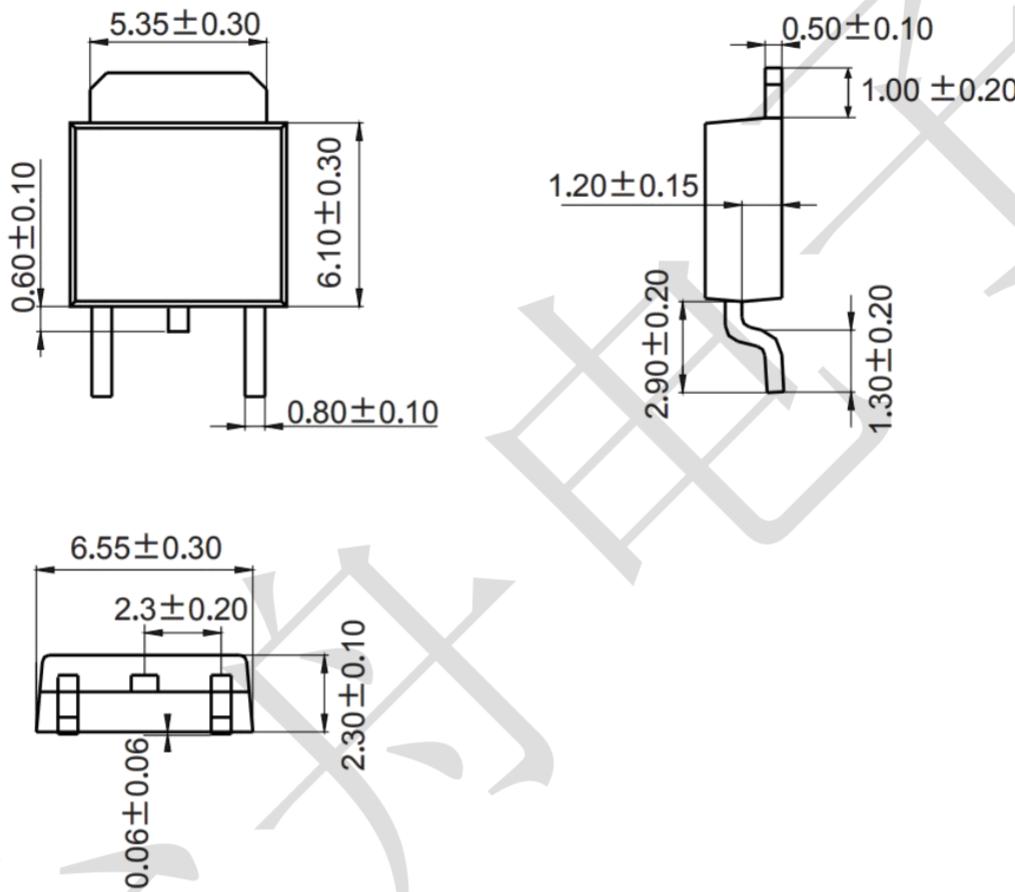
Forward Characteristic of  
Reverse Diode



Gate Threshold Voltage v.s.  
Junction Temperature

**Package Outline Dimensions (unit: mm)**

TO-252



**Mounting Pad Layout (unit: mm)**

